

Circuit Card Assembly and Test

Fact Sheet

COBHAM

January 2016

The most important thing we build is trust

OVERVIEW

The Aeroflex Colorado Springs, Inc., dba Cobham Semiconductor Solution Circuit Card Assembly capability consists of complete assembly, test and conformal coat in a high mix/low to medium volume operation. Cobham's process equipment and test capabilities provide for state-of-the-art manufacturing for military, commercial Space and aerospace markets.

Our new Automated Line was introduced in Summer 2015.

We offer build to print, prototype, engineering, qualification and quick turn, typically less than 6 weeks from receipt of components and documents.

Cobham uses best commercial practices combined with IPC-A-610 / ANSI-J-STD-001 (with latest space addendum), ISO 9001:2008 with AS-9100:2004 Rev C and NASA 8739 Certifications.

We are an approved supplier for Tier 1 companies.



Value-Added Services for:

- Advanced Package Engineering
 - Hybrids
 - Chip-on-Board
 - Flip Chip/Flip Chip on Flex
 - Flex boards
 - Package assembly



AEROSPACE ADVANTAGES

- High-reliability standards for design and production
- Board layout
- Low volume orders accepted
- Supplier and BOM Management as part of our Supply Chain Organization
- Access to standard and ASIC products (QML Q, T, V products)

CCA SERVICES

- Quick turn assembly
- Material management
- Flying probe testing/customer supplied functional testing
- Dock to stock with Aeroflex ICs
- SMT, through-hole, test and coat
- Customer specified processes
- Design for manufacturability

MATERIAL MANAGEMENT

- Full turnkey or consigned material acquisition
- Supplier management, obsolescence, counterfeit
- BOM management, GIDEP and DSMS
- Value-added component screening
- On-site radiation test and other material screening